

WP934EB/2YD

T-1 (3mm) Bi-Level Circuit Board Indicator



DESCRIPTION

• The Yellow source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Yellow Light Emitting Diode

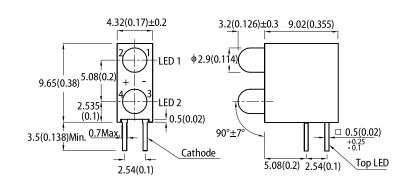
FEATURES

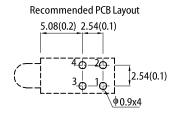
- · Pre-trimmed leads for pc mounting
- · Black case enhances contrast ratio
- · High reliability life measured in years
- Housing UL rating: 94V-0
- Housing material: Type 66 nylon
- RoHS compliant

APPLICATIONS

- Status indicator
- Illuminator
- · Signage applications
- · Decorative and entertainment lighting
- · Commercial and residential architectural lighting

PACKAGE DIMENSIONS





- All dimensions are in millimeters (inches).
 Tolerance is ±0.25(0.01") unless otherwise noted.
- Lead spacing is measured where the leads emerge from the package.
 The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice

SELECTION GUIDE

Part Number	Emitting Color (Material)	Lens Type	Iv (mcd) @ 10mA [2]		Viewing Angle [1]
			Min.	Тур.	201/2
WP934EB/2YD	Yellow (GaAsP/GaP)	Yellow Diffused	8	15	50°

Notes.

1. 01/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.

2. Luminous intensity / luminous flux: +/-15%.

3. Luminous intensity value is traceable to CIE127-2007 standards.





ELECTRICAL / OPTICAL CHARACTERISTICS at T_A=25°C

Parameter	Symbol	Emitting Color	Value		Unit
Parameter	Symbol	Emitting Color	Тур.	Max.	Offic
Wavelength at Peak Emission I _F = 10mA	λ_{peak}	Yellow	590	-	nm
Dominant Wavelength I _F = 10mA	λ _{dom} ^[1]	Yellow	588	-	nm
Spectral Bandwidth at 50% Φ REL MAX I _F = 10mA	Δλ	Yellow	35	-	nm
Capacitance	С	Yellow	20	-	pF
Forward Voltage I _F = 10mA	V _F ^[2]	Yellow	1.95	2.4	V
Reverse Current (V _R = 5V)	I _R	Yellow	-	10	μА
Temperature Coefficient of λ_{peak} I_F = 10mA, -10°C \leq T \leq 85°C	$TC_{\lambda peak}$	Yellow	0.12	-	nm/°C
Temperature Coefficient of λ_{dom} I _F = 10mA, -10°C \leq T \leq 85°C	TC _{λdom}	Yellow	0.07	-	nm/°C
Temperature Coefficient of V_F I_F = 10mA, -10°C \leq T \leq 85°C	TC _V	Yellow	-2	-	mV/°C

Notes:

ABSOLUTE MAXIMUM RATINGS at T_A=25°C

Parameter	Symbol	Value	Unit	
Power Dissipation	P _D	75	mW	
Reverse Voltage	V_R	5	V	
Junction Temperature	T _j	110	°C	
Operating Temperature	T _{op}	-40 To +85	°C	
Storage Temperature	T _{stg}	-40 To +85	°C	
DC Forward Current	I _F	30	mA	
Peak Forward Current	I _{FM} ^[1]	140	mA	
Electrostatic Discharge Threshold (HBM)	-	8000	V	
Thermal Resistance (Junction / Ambient)	R _{th JA} ^[2]	690	°C/W	
Thermal Resistance (Junction / Solder point)	R _{th JS} ^[2]	450	°C/W	
Lead Solder Temperature [3]		260°C For 3 Seconds		
Lead Solder Temperature [4]		260°C For 5 Seconds		

Notes:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.

2. R_{th JA}, R_{th JS} Results from mounting on PC board FR4 (pad size ≥ 16 mm² per pad).

3. 2mm below package base.

4. 5mm below package base.

5. Relative humidity levels maintained between 40% and 60% in production area are recommended to avoid the build-up of static electricity – Ref JEDEC/JESD625-A and JEDEC/J-STD-033.

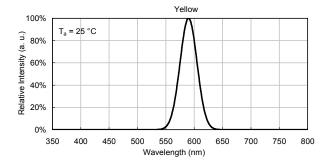


The dominant wavelength (λd) above is the setup value of the sorting machine. (Tolerance λd:±1nm.)
 Forward voltage: ±0.1V.
 Wavelength value is traceable to CIE127-2007 standards.
 Excess driving current and / or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

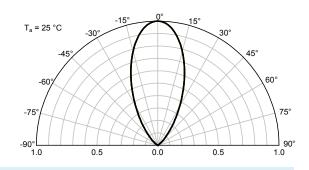


TECHNICAL DATA

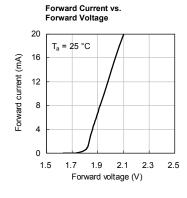
RELATIVE INTENSITY vs. WAVELENGTH

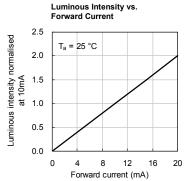


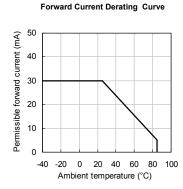
SPATIAL DISTRIBUTION

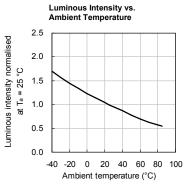


YELLOW

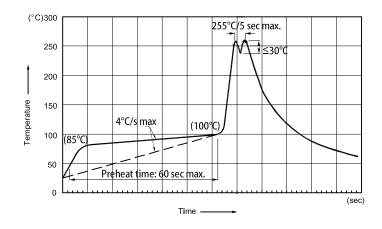








RECOMMENDED WAVE SOLDERING PROFILE



Notes

- Recommend pre-heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of 260 $^\circ\text{C}$
- 2. Peak wave soldering temperature between 245°C ~ 255°C for 3 sec (5 sec max).

 3. Do not apply stress to the epoxy resin while the temperature is above 85°C.

 4. Fixtures should not incur stress on the component when mounting and during soldering process.
- SAC 305 solder alloy is recommended.
 No more than one wave soldering pass.

PACKING & LABEL SPECIFICATIONS

